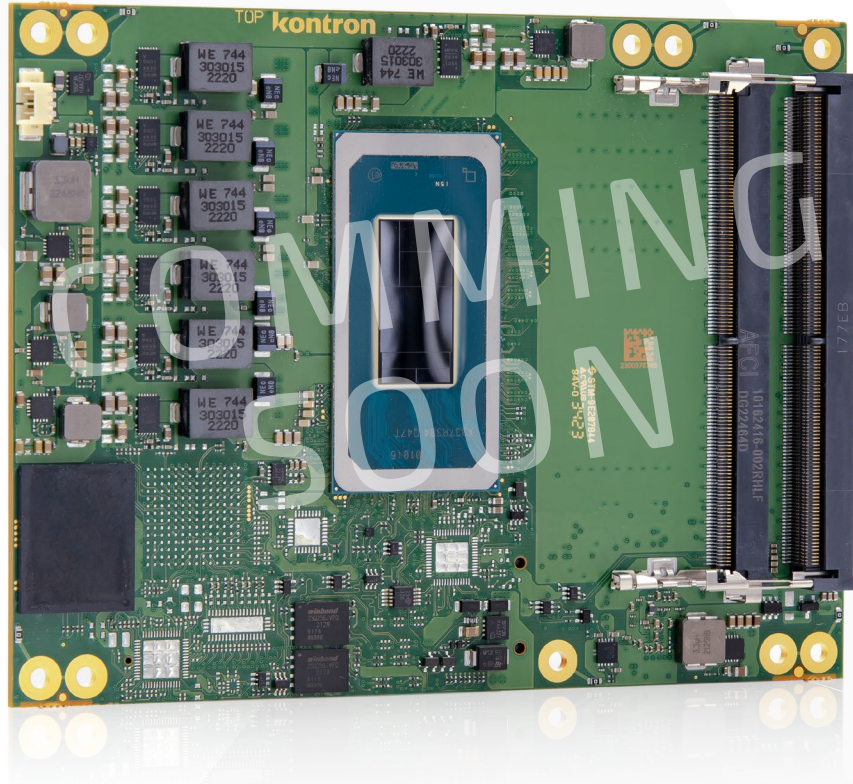


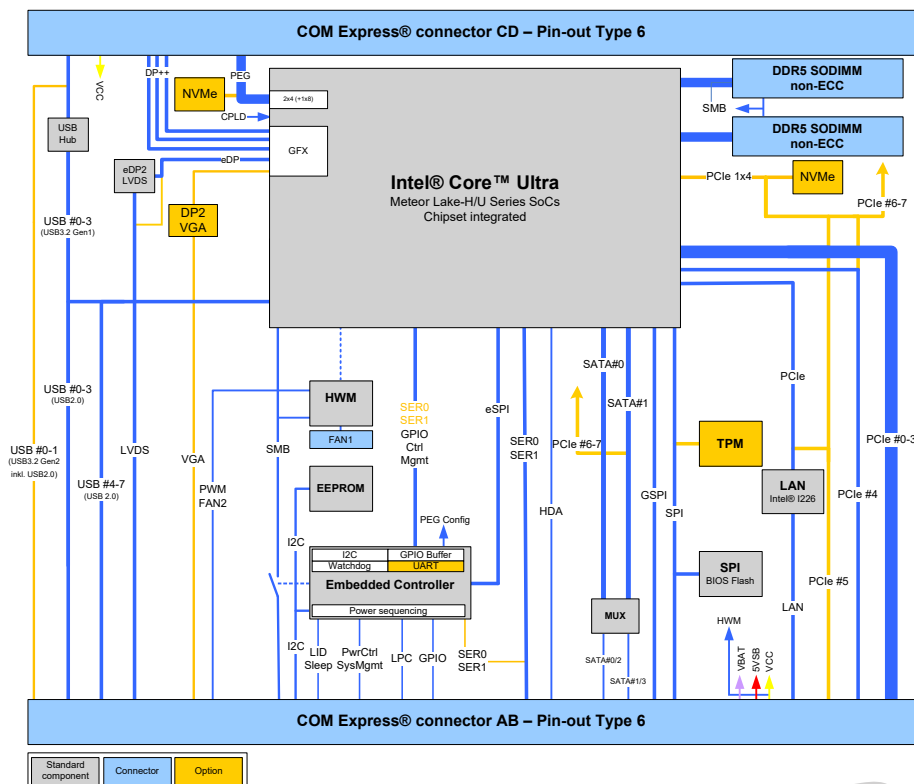
COMe-bMT6



COM Express® Basic Type 6 with Intel® Core™ Ultra Meteor Lake-H/U Series

- Intel® Arc™ Graphics architecture with up to 8 Xe-Cores (128EUs)
- Integrated NPU for dedicated AI acceleration
- Up to 96 GByte DDR5 memory
- Up to 2.5 Gb Ethernet
- Optional NVMe SSDs onboard

COMPLIANCE	COM Express® Basic Pin-out Type 6
DIMENSIONS (H X W)	125 x 95 mm
CPU	Intel® Core™ Ultra Meteor Lake-H/U family For details see table (CPU variants) given below
CHIPSET	Integrated SoC
MAIN MEMORY	2x DDR5 SO-DIMM with up to 48 GByte per channel (non-ECC) IB ECC support (dependent on used OS)
GRAPHICS CONTROLLER	Intel® Arc™ Graphics on H-series Intel® Graphics on U-series
ETHERNET CONTROLLER	Intel® I226LM
ETHERNET	Up to 2.5Gb Ethernet
STORAGE	2x SATA 6Gb/s
FLASH ONBOARD	Up to 2x NVMe SSD (on request)
PCI EXPRESS®	5x PCIe 3.0 (On request: 6x without Ethernet, up to 8x without Ethernet & SATA or alternatively 4x1+1x4 config with Ethernet & SATA) 2x4 PCIe 4.0 on PEG Lanes #0-7 1x8 PCIe 4.0 on PEG Lanes #8-15 (H-series only)
DISPLAY	DDI1: DP++, DDI2: DP++, DDI3: DP++, VGA: -, LVDS: Dual Channel 18/24bit
USB	Up to 4x USB 3.2 Gen1 (incl. USB 2.0) + 4x USB 2.0
SERIAL	2x serial interface (RX/TX only)
AUDIO	High Definition Audio interface
OTHER FEATURES	(G)SPI, LPC, SMB, Fast I²C, Staged Watchdog, RTC
SPECIAL FEATURES	Trusted Platform Module TPM 2.0 (on request)
FEATURES ON REQUEST	vPRO (AMT/TXT/AES Support) on dedicated SKUs, eDP instead of LVDS, VGA, USB-C, up to 8x PCIe x1 w/o Ethernet & SATA or 4x1+1x4 w/ Ethernet & SATA , up to 2x NVMe SSDs, discrete TPM
POWER MANAGEMENT	ACPI 6.0
POWER SUPPLY	8.5 V – 20 V Wide Range, Single Supply Power
BIOS	AMI Aptio V
OPERATING SYSTEM	Windows®10/11, Linux, VxWorks (project based)
TEMPERATURE	Commercial temperature: 0 °C to +60 °C operating, -30 °C to +85 °C non-operating
HUMIDITY	93 % relative Humidity at 40 °C, non-condensing (according to IEC 60068-2-78)



CPU Variants

INTEL® CORE™ ULTRA METEOR LAKE H-SERIES (28W)		
CPU	Core™ Ultra 7-155H	Core™ Ultra i5-125H
CORES	16	14
NUMBER OF P-CORES	6	4
FREQUENCY BASE/TURBO (P-CORES)	1.4/4.8 GHz	1.2/4.5 GHz
NUMBER OF E-CORES	8	8
FREQUENCY BASE/TURBO (E-CORES)	0.9/3.8 GHz	0.7/3.6 GHz
NUMBER OF LPE-CORES	2	2
TDP	28/20 W	28/20 W
CACHE	24 MByte	18 MByte
IBECC	dependent on used OS	dependent on used OS
TCC/TSN	no	no
INTEL® CORE™ ULTRA METEOR LAKE U-SERIES (15W)		
CPU	Core™ Ultra 7-155U	Core™ Ultra 5-125U
CORES	12	12
NUMBER OF P-CORES	2	2
FREQUENCY BASE/TURBO (P-CORES)	1.7/4.8 GHz	1.3/4.3 GHz
NUMBER OF E-CORES	8	8
FREQUENCY BASE/TURBO (E-CORES)	1.2/3.8 GHz	0.8/3.6 GHz
NUMBER OF LPE-CORES	2	2
TDP	15/12 W	15/12 W
CACHE	12 MByte	12 MByte
IBECC	dependent on used OS	dependent on used OS
TCC/TSN	no	no

PART NO.	CPU	PCH	MEMORY	MEM TYPE	FLASH	OP. TEMPERATURE
38042-0000-14-7	Ultra 7-155H	-	SO-DIMM	non-ECC	-	0 °C - 60 °C
38042-0000-12-5	Ultra 5-125H	-	SO-DIMM	non-ECC	-	0 °C - 60 °C
38042-0000-17-7	Ultra 7-155U	-	SO-DIMM	non-ECC	-	0 °C - 60 °C
38042-0000-13-5	Ultra 5-125U	-	SO-DIMM	non-ECC	-	0 °C - 60 °C

Carrier

ARTICLE	PART NO.	DESCRIPTION
COME EVAL CARRIER2 T6	38116-0000-00-0	COM Express® Evaluation Carrier Type 6
COME EVAL CARRIER2 T6 5mm	38116-0000-00-5	COM Express® Evaluation Carrier Type 6 with 5 mm COMe connector

Cooling

ARTICLE	PART NO.	DESCRIPTION
HSP COME-BMT6 CU-CORE THREADED	38042-0000-99-0	Heatspreader for COM-bMT6, Cu-core, threaded mounting holes
HSP COME-BMT6 CU-CORE THROUGH	38042-0000-99-1	Heatspreader for COM-bMT6, Cu-core, through mounting holes
HSK COME-BASIC ACTIVE (W/O HSP)	38025-0000-99-0C05	Active Cooler for COMe-bMT6/bRP6/bxL6/bV26/bDV7/bID7 to be mounted on HSP
HSK COME-BASIC PASSIVE (W/O HSP)	38025-0000-99-0C06	Passive Cooler for COMe-bxL6/bDV7 to be mounted on HSP

Memory

PART NO.	MIN. SPEC.	SIZE	ECC	OP. TEMPERATURE
97040-4856-BRP6	DDR5-5600	48 GByte	no	0 °C - 60 °C
97040-3256-BRP6	DDR5-5600	32 GByte	no	0 °C - 60 °C
97040-1656-BRP6	DDR5-5600	16 GByte	no	0 °C - 60 °C
97040-0856-BRP6	DDR5-5600	8 GByte	no	0 °C - 60 °C

contact@steliau.fr 

steliau.fr 

6 rue des Gémeaux, 94150, Rungis 